

**AMENDMENT TRANSMITTAL LETTER (Large Entity)**

Applicant(s): Toshimichi Kurihara, et al.

Docket No.

14872

Serial No.

09/942,445

Filing Date

August 30, 2001

Examiner

Nema O. Berezny

Group Art Unit

2813

Invention: SEMICONDUCTOR DEVICE IN A RESIN SEALED PACKAGE WITH A RADIATING

PLATE AND MANUFACTURING METHOD THEREOF

**TO THE COMMISSIONER FOR PATENTS:**

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

**CLAIMS AS AMENDED**

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	14 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	3 -	3 =	0 x	\$86.00	\$0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$0.00

- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. \_\_\_\_\_ in the amount of \_\_\_\_\_
- ☐ A check in the amount of \_\_\_\_\_ to cover the filing fee is enclosed.
- ☒ The Director is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **19-1013/SSMP**
- ☒ Any additional filing fees required under 37 C.F.R. 1.16.
- ☒ Any patent application processing fees under 37 CFR 1.17.

  
Signature

Dated: February 24, 2004

Aasheesh V. Shravah  
Registration No. 54,445  
SCULLY, SCOTT, MURPHY & PRESSER  
400 Garden City Plaza  
Garden City, NY 11530  
(516) 742-4343  
AVS:jap

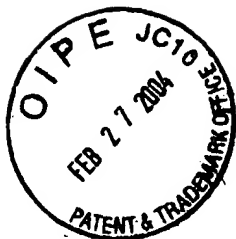
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicants:** Toshimichi Kurihara, et al.                      **Examiner:** Nema O. Berezny  
**Serial No.:** 09/942,445    **Unit:** 2813  
**Filed:** August 30, 2001    **Docket:** 14872  
**For:** SEMICONDUCTOR DEVICE IN A                      **Dated:** February 24, 2004  
RESIN SEALED PACKAGE WITH  
A RADIATING PLATE AND  
MANUFACTURING METHOD THEREOF

**Conf. No.:** 7920

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE**

Sir:


In response to the Official Action dated November 24, 2003, Applicants respectfully request reconsideration of the above-identified application in light of the following amendments and remarks:

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 24, 2004.

Dated: February 24, 2004

  
Aasheesh V. Shravah